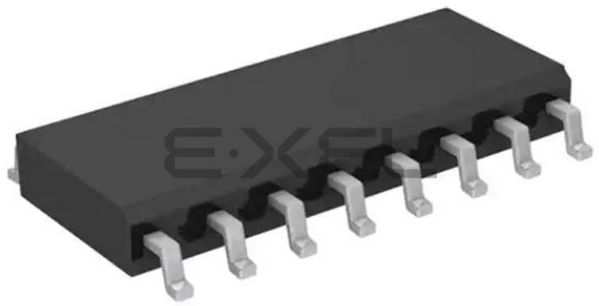

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.154", 3.90mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f865-c-isr

Table 1.5. Internal Oscillators

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
High Frequency Oscillator (24.5 MHz)						
Oscillator Frequency	f_{HFOSC}	Full Temperature and Supply Range	24	24.5	25	MHz
Power Supply Sensitivity	PSS_{HFOSC}	T_A = 25 °C	—	0.5	—	%/V
Temperature Sensitivity	TS_{HFOSC}	V_{DD} = 3.0 V	—	40	—	ppm/°C
Low Frequency Oscillator (80 kHz)						
Oscillator Frequency	f_{LFOSC}	Full Temperature and Supply Range	75	80	85	kHz
Power Supply Sensitivity	PSS_{LFOSC}	T_A = 25 °C	—	0.05	—	%/V
Temperature Sensitivity	TS_{LFOSC}	V_{DD} = 3.0 V	—	65	—	ppm/°C

Table 1.6. External Clock Input

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
External Input CMOS Clock Frequency (at EXTCLK pin)	f_{CMOS}		0	—	25	MHz
External Input CMOS Clock High Time	t_{CMOSH}		18	—	—	ns
External Input CMOS Clock Low Time	t_{CMOSL}		18	—	—	ns

Table 1.10. Comparators

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Positive Hysteresis Mode 3 (CPnMD = 11)	HYS_{CP+}	CPnHYP = 00	—	1.5	—	mV
		CPnHYP = 01	—	4	—	mV
		CPnHYP = 10	—	8	—	mV
		CPnHYP = 11	—	16	—	mV
Negative Hysteresis Mode 3 (CPnMD = 11)	HYS_{CP-}	CPnHYN = 00	—	-1.5	—	mV
		CPnHYN = 01	—	–4	—	mV
		CPnHYN = 10	—	–8	—	mV
		CPnHYN = 11	—	–16	—	mV
Input Range (CP+ or CP–)	V_{IN}		-0.25	—	V_{DD}+0.25	V
Input Pin Capacitance	C_{CP}		—	7.5	—	pF
Common-Mode Rejection Ratio	$CMRR_{CP}$		—	70	—	dB
Power Supply Rejection Ratio	$PSRR_{CP}$		—	72	—	dB
Input Offset Voltage	V_{OFF}	T_A = 25 °C	-10	0	10	mV
Input Offset Tempco	TC_{OFF}		—	3.5	—	µV/°C

Table 3.1. Pin Definitions for C8051F850/1/2/3/4/5-GU and C8051F850/1/2/3/4/5-IU

Pin Name	Type	Pin Numbers	Crossbar Capability	Additional Digital Functions	Analog Functions
P1.0	Standard I/O	18	Yes	P1MAT.0	ADC0.8 CP1P.0 CP1N.0
P1.1	Standard I/O	17	Yes	P1MAT.1	ADC0.9 CP1P.1 CP1N.1
P1.2	Standard I/O	16	Yes	P1MAT.2	ADC0.10 CP1P.2 CP1N.2
P1.3	Standard I/O	15	Yes	P1MAT.3	ADC0.11 CP1P.3 CP1N.3
P1.4	Standard I/O	14	Yes	P1MAT.4	ADC0.12 CP1P.4 CP1N.4
P1.5	Standard I/O	11	Yes	P1MAT.5	ADC0.13 CP1P.5 CP1N.5
P1.6	Standard I/O	10	Yes	P1MAT.6	ADC0.14 CP1P.6 CP1N.6
P1.7	Standard I/O	9	Yes	P1MAT.7	ADC0.15 CP1P.7 CP1N.7
P2.0 / C2D	Standard I/O / C2 Debug Data	8			
P2.1	Standard I/O	12			

3.3. C8051F860/1/2/3/4/5 SOIC16 Pin Definitions

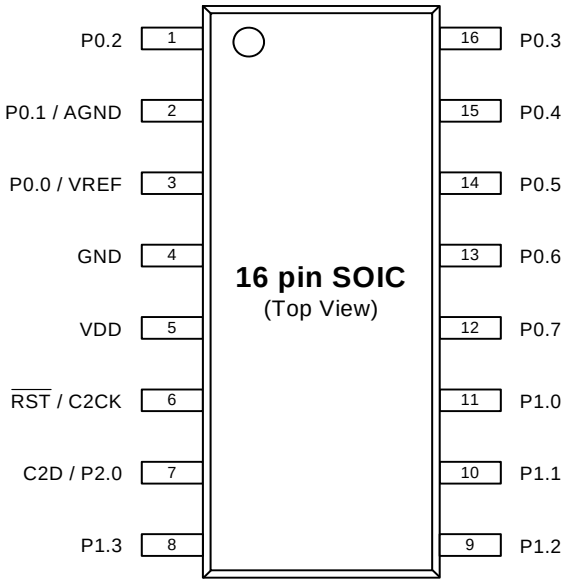

Figure 3.3. C8051F860/1/2/3/4/5-GS and C8051F860/1/2/3/4/5-IS Pinout

Table 3.3. Pin Definitions for C8051F860/1/2/3/4/5-GS and C8051F860/1/2/3/4/5-IS

Pin Name	Type	Pin Numbers	Crossbar Capability	Additional Digital Functions	Analog Functions
GND	Ground	4			
VDD	Power	5			
RST / C2CK	Active-low Reset / C2 Debug Clock	6			
P0.0	Standard I/O	3	Yes	P0MAT.0 INT0.0 INT1.0	ADC0.0 CP0P.0 CP0N.0

Table 4.1. Product Selection Guide

Ordering Part Number	Flash Memory (kB)	RAM (Bytes)	Digital Port I/Os (Total)	Number of ADC0 Channels	I/O with Comparator 0/1 Inputs	Pb-free (RoHS Compliant)	AEC-Q100 Qualified	Temperature Range	Package
C8051F850-C-GM	8	512	16	15	15	✓	✓	-40 to 85 °C	QFN-20
C8051F850-C-GU	8	512	18	16	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F851-C-GM	4	512	16	15	15	✓	✓	-40 to 85 °C	QFN-20
C8051F851-C-GU	4	512	18	16	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F852-C-GM	2	256	16	15	15	✓	✓	-40 to 85 °C	QFN-20
C8051F852-C-GU	2	256	18	16	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F853-C-GM	8	512	16	—	15	✓	✓	-40 to 85 °C	QFN-20
C8051F853-C-GU	8	512	18	—	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F854-C-GM	4	512	16	—	15	✓	✓	-40 to 85 °C	QFN-20
C8051F854-C-GU	4	512	18	—	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F855-C-GM	2	256	16	—	15	✓	✓	-40 to 85 °C	QFN-20
C8051F855-C-GU	2	256	18	—	16	✓	✓	-40 to 85 °C	QSOP-24
C8051F860-C-GS	8	512	13	12	12	✓	✓	-40 to 85 °C	SOIC-16
C8051F861-C-GS	4	512	13	12	12	✓	✓	-40 to 85 °C	SOIC-16
C8051F862-C-GS	2	256	13	12	12	✓	✓	-40 to 85 °C	SOIC-16
C8051F863-C-GS	8	512	13	—	12	✓	✓	-40 to 85 °C	SOIC-16
C8051F864-C-GS	4	512	13	—	12	✓	✓	-40 to 85 °C	SOIC-16
C8051F865-C-GS	2	256	13	—	12	✓	✓	-40 to 85 °C	SOIC-16

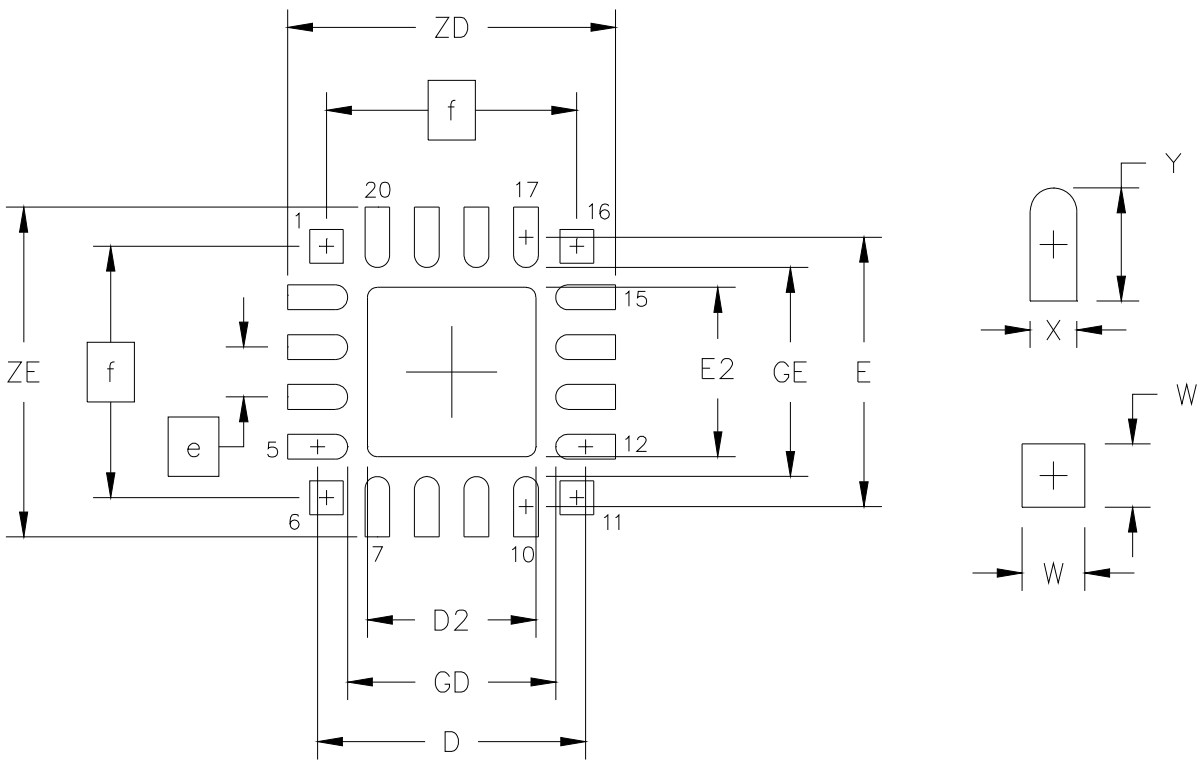

Figure 6.2. QFN-20 Landing Diagram

Table 6.2. QFN-20 Landing Diagram Dimensions

Symbol	Millimeters		Symbol	Millimeters	
	Min	Max		Min	Max
D	2.71 REF		GE	2.10	—
D2	1.60	1.80	W	—	0.34
e	0.50 BSC		X	—	0.28
E	2.71 REF		Y	0.61 REF	
E2	1.60	1.80	ZE	—	3.31
f	2.53 BSC		ZD	—	3.31
GD	2.10	—			

Notes: General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on IPC-SM-782 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Notes: Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Notes: Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1 for the perimeter pads.
4. A 1.45 x 1.45 mm square aperture should be used for the center pad. This provides approximately 70% solder paste coverage on the pad, which is optimum to assure correct component stand-off.

Notes: Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

8.1. Program Memory

The CIP-51 core has a 64 kB program memory space. The C8051F85x/86x family implements 8 kB, 4 kB or 2 kB of this program memory space as in-system, re-programmable flash memory. The last address in the flash block (0x1FFF on 8 kB devices, 0x0FFF on 4 kB devices and 0x07FF on 2 kB devices) serves as a security lock byte for the device, and provides read, write and erase protection. Addresses above the lock byte within the 64 kB address space are reserved.

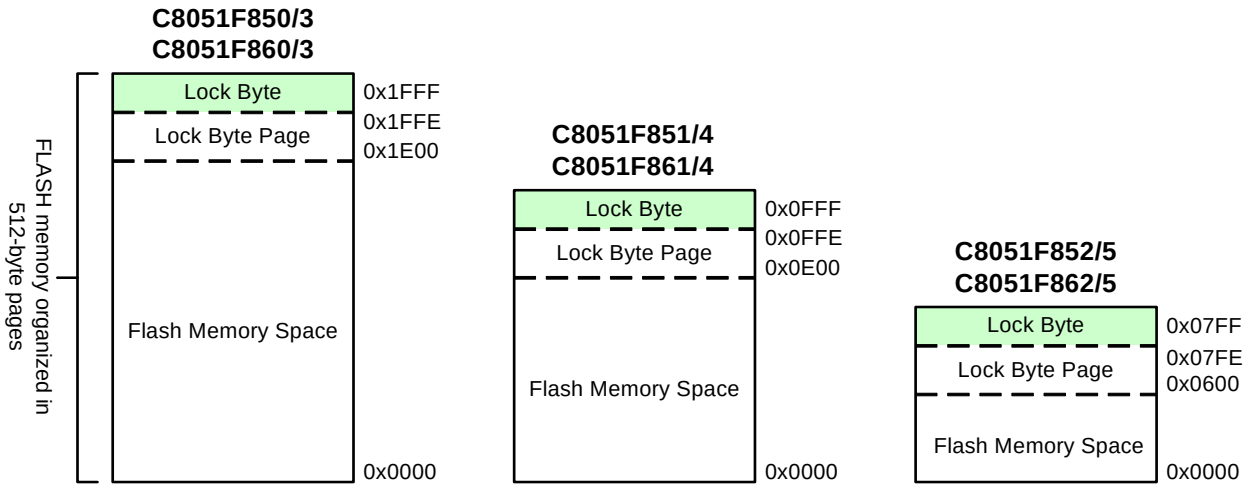

Figure 8.2. Flash Program Memory Map

8.1.1. MOVX Instruction and Program Memory

The MOVX instruction in an 8051 device is typically used to access external data memory. On the C8051F85x/86x devices, the MOVX instruction is normally used to read and write on-chip XRAM, but can be re-configured to write and erase on-chip flash memory space. MOVC instructions are always used to read flash memory, while MOVX write instructions are used to erase and write flash. This flash access feature provides a mechanism for the C8051F85x/86x to update program code and use the program memory space for non-volatile data storage. Refer to Section “10. Flash Memory” on page 61 for further details.

8.2. Data Memory

The C8051F85x/86x device family includes up to 512 bytes of RAM data memory. 256 bytes of this memory is mapped into the internal RAM space of the 8051. On devices with 512 bytes total RAM, 256 additional bytes of memory are available as on-chip “external” memory. The data memory map is shown in Figure 8.1 for reference.

8.2.1. Internal RAM

There are 256 bytes of internal RAM mapped into the data memory space from 0x00 through 0xFF. The lower 128 bytes of data memory are used for general purpose registers and scratch pad memory. Either direct or indirect addressing may be used to access the lower 128 bytes of data memory. Locations 0x00 through 0x1F are addressable as four banks of general purpose registers, each bank consisting of eight byte-wide registers. The next 16 bytes, locations 0x20 through 0x2F, may either be addressed as bytes or as 128 bit locations accessible with the direct addressing mode.

Register 10.2. FLKEY: Flash Lock and Key

Bit	7	6	5	4	3	2	1	0
Name	FLKEY							
Type	RW							
Reset	0	0	0	0	0	0	0	0
SFR Address: 0xB7								

Table 10.3. FLKEY Register Bit Descriptions

Bit	Name	Function
7:0	FLKEY	**Flash Lock and Key Register.** Write: This register provides a lock and key function for flash erasures and writes. Flash writes and erases are enabled by writing 0xA5 followed by 0xF1 to the FLKEY register. Flash writes and erases are automatically disabled after the next write or erase is complete. If any writes to FLKEY are performed incorrectly, or if a flash write or erase operation is attempted while these operations are disabled, the flash will be permanently locked from writes or erasures until the next device reset. If an application never writes to flash, it can intentionally lock the flash by writing a non-0xA5 value to FLKEY from software. Read: When read, bits 1-0 indicate the current flash lock state. 00: Flash is write/erase locked. 01: The first key code has been written (0xA5). 10: Flash is unlocked (writes/erases allowed). 11: Flash writes/erases are disabled until the next reset.

12. Interrupts

The C8051F85x/86x includes an extended interrupt system supporting multiple interrupt sources with two priority levels. The allocation of interrupt sources between on-chip peripherals and external input pins varies according to the specific version of the device. Each interrupt source has one or more associated interrupt-pending flag(s) located in an SFR. When a peripheral or external source meets a valid interrupt condition, the associated interrupt-pending flag is set to logic 1.

If interrupts are enabled for the source, an interrupt request is generated when the interrupt-pending flag is set. As soon as execution of the current instruction is complete, the CPU generates an LCALL to a predetermined address to begin execution of an interrupt service routine (ISR). Each ISR must end with an RETI instruction, which returns program execution to the next instruction that would have been executed if the interrupt request had not occurred. If interrupts are not enabled, the interrupt-pending flag is ignored by the hardware and program execution continues as normal. The interrupt-pending flag is set to logic 1 regardless of the interrupt's enable/disable state.

Each interrupt source can be individually enabled or disabled through the use of an associated interrupt enable bit in an SFR (IE and EIE1). However, interrupts must first be globally enabled by setting the EA bit in the IE register to logic 1 before the individual interrupt enables are recognized. Setting the EA bit to logic 0 disables all interrupt sources regardless of the individual interrupt-enable settings.

Some interrupt-pending flags are automatically cleared by the hardware when the CPU vectors to the ISR. However, most are not cleared by the hardware and must be cleared by software before returning from the ISR. If an interrupt-pending flag remains set after the CPU completes the return-from-interrupt (RETI) instruction, a new interrupt request will be generated immediately and the CPU will re-enter the ISR after the completion of the next instruction.

12.1. MCU Interrupt Sources and Vectors

The C8051F85x/86x MCUs support interrupt sources for each peripheral on the device. Software can simulate an interrupt by setting any interrupt-pending flag to logic 1. If interrupts are enabled for the flag, an interrupt request will be generated and the CPU will vector to the ISR address associated with the interrupt-pending flag. MCU interrupt sources, associated vector addresses, priority order and control bits are summarized in Table 12.1. Refer to the datasheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).

12.1.1. Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be preempted by a high priority interrupt. A high priority interrupt cannot be preempted. Each interrupt has an associated interrupt priority bit in an SFR (IP or EIP1) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate, given in Table 12.1.

12.1.2. Interrupt Latency

Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the fastest possible response time is 5 system clock cycles: 1 clock cycle to detect the interrupt and 4 clock cycles to complete the LCALL to the ISR. If an interrupt is pending when a RETI is executed, a single instruction is executed before an LCALL is made to service the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) occurs when the CPU is performing an RETI instruction followed by a DIV as the next instruction. In this case, the response time is 18 system clock cycles: 1 clock cycle to detect the interrupt, 5 clock cycles to execute the RETI, 8 clock

14. Analog-to-Digital Converter (ADC0)

The ADC is a successive-approximation-register (SAR) ADC with 12-, 10-, and 8-bit modes, integrated track-and-hold and a programmable window detector. These different modes allow the user to trade off speed for resolution. ADC0 also has an autonomous low-power burst mode which can automatically enable ADC0, capture and accumulate samples, then place ADC0 in a low power shutdown mode without CPU intervention. It also has a 16-bit accumulator that can automatically oversample and average the ADC results.

The ADC is fully configurable under software control via several registers. The ADC0 operates in single-ended mode and may be configured to measure different signals using the analog multiplexer. The voltage reference for the ADC is selectable between internal and external reference sources.

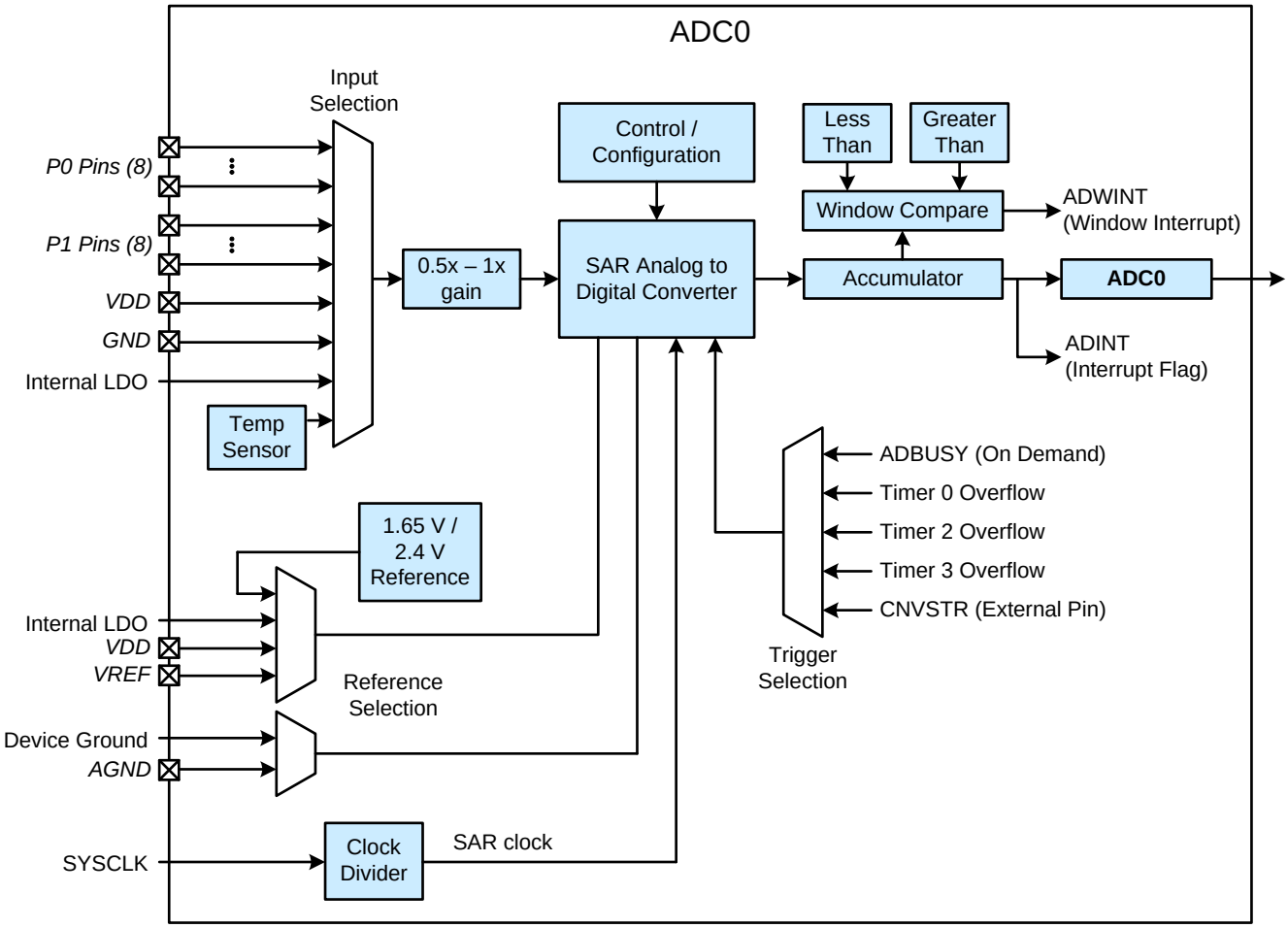

Figure 14.1. ADC0 Functional Block Diagram

Register 15.5. B: B Register

Bit	7	6	5	4	3	2	1	0
Name	B							
Type	RW							
Reset	0	0	0	0	0	0	0	0
SFR Address: 0xF0 (bit-addressable)								

Table 15.6. B Register Bit Descriptions

Bit	Name	Function
7:0	B	**B Register.** This register serves as a second accumulator for certain arithmetic operations.

Table 17.1. CMP0 Positive Input Multiplexer Channels

CMXP Setting in Register CPT0MX	Signal Name	QSOP24 Pin Name	QFN20 Pin Name	SOIC16 Pin Name
0000	CP0P.0	P0.0	P0.0	P0.0
0001	CP0P.1	P0.1	P0.1	P0.1
0010	CP0P.2	P0.2	P0.2	P0.2
0011	CP0P.3	P0.3	P0.3	P0.3
0100	CP0P.4	P0.4	P0.4	P0.4
0101	CP0P.5	P0.5	P0.5	P0.5
0110	CP0P.6	P0.6	P0.6	Reserved
0111	CP0P.7	P0.7	P0.7	Reserved
1000	LDO	Internal 1.8 V LDO Output		
1001-1111	None	No connection		

Table 17.2. CMP0 Negative Input Multiplexer Channels

CMXN Setting in Register CPT0MX	Signal Name	QSOP24 Pin Name	QFN20 Pin Name	SOIC16 Pin Name
0000	CP0N.0	P0.0	P0.0	P0.0
0001	CP0N.1	P0.1	P0.1	P0.1
0010	CP0N.2	P0.2	P0.2	P0.2
0011	CP0N.3	P0.3	P0.3	P0.3
0100	CP0N.4	P0.4	P0.4	P0.4
0101	CP0N.5	P0.5	P0.5	P0.5
0110	CP0N.6	P0.6	P0.6	Reserved
0111	CP0N.7	P0.7	P0.7	Reserved
1000	GND	GND		
1001-1111	None	No connection		

18.6. CRC Control Registers

Register 18.1. CRC0CN: CRC0 Control

Bit	7	6	5	4	3	2	1	0
Name	Reserved				CRCINIT	CRCVAL	Reserved	CRCPNT
Type	R				RW	RW	R	RW
Reset	0	0	0	1	0	0	0	0
SFR Address: 0xCE								

Table 18.2. CRC0CN Register Bit Descriptions

Bit	Name	Function
7:4	Reserved	Must write reset value.
3	CRCINIT	**CRC Result Initialization Bit.** Writing a 1 to this bit initializes the entire CRC result based on CRCVAL.
2	CRCVAL	**CRC Set Value Initialization Bit.** This bit selects the set value of the CRC result. 0: CRC result is set to 0x0000 on write of 1 to CRCINIT. 1: CRC result is set to 0xFFFF on write of 1 to CRCINIT.
1	Reserved	Must write reset value.
0	CRCPNT	**CRC Result Pointer.** Specifies the byte of the CRC result to be read/written on the next access to CRC0DAT. This bit will automatically toggle upon each read or write. 0: CRC0DAT accesses bits 7-0 of the 16-bit CRC result. 1: CRC0DAT accesses bits 15-8 of the 16-bit CRC result.
Note: Upon initiation of an automatic CRC calculation, the three cycles following a write to CRC0CN that initiate a CRC operation must only contain instructions which execute in the same number of cycles as the number of bytes in the instruction. An example of such an instruction is a 3-byte MOV that targets the CRC0FLIP register. When programming in C, the dummy value written to CRC0FLIP should be a non-zero value to prevent the compiler from generating a 2-byte MOV instruction.		

21.2.3. Assigning Port I/O Pins to Fixed Digital Functions

Fixed digital functions include external clock input as well as external event trigger functions, which can be used to trigger events such as an ADC conversion, fire an interrupt or wake the device from idle mode when a transition occurs on a digital I/O pin. The fixed digital functions do not require dedicated pins and will function on both GPIO pins and pins in use by the crossbar. Fixed digital functions cannot be used on pins configured for analog I/O. Table 21.3 shows all available fixed digital functions and the potential mapping of port I/O to each function.

Table 21.3. Port I/O Assignment for Fixed Digital Functions

Function	Potentially Assignable Port Pins	SFR(s) used for Assignment
External Interrupt 0	P0.0 - P0.7	IT01CF
External Interrupt 1	P0.0 - P0.7	IT01CF
Conversion Start (CNVSTR)	P0.6	ADC0CN
External Clock Input (EXTCLK)	P0.3	OSCXCN
Port Match	P0.0 - P1.7	P0MASK, P0MAT P1MASK, P1MAT

22.1. Power-On Reset

During power-up, the POR circuit will fire. When POR fires, the device is held in a reset state and the $\overline{RST}$ pin is driven low until V_{DD} settles above V_{RST}. Two delays are present during the supply ramp time. First, a delay will occur before the POR circuitry fires and pulls the $\overline{RST}$ pin low. A second delay occurs before the device is released from reset; the delay decreases as the V_{DD} ramp time increases (V_{DD} ramp time is defined as how fast V_{DD} ramps from 0 V to V_{RST}). Figure 22.2. plots the power-on reset timing. For ramp times less than 1 ms, the power-on reset time (T_{POR}) is typically less than 0.3 ms. Additionally, the power supply must reach V_{RST} before the POR circuit will release the device from reset.

On exit from a power-on reset, the PORSF flag (RSTSRC.1) is set by hardware to logic 1. When PORSF is set, all of the other reset flags in the RSTSRC Register are indeterminate (PORSF is cleared by all other resets). Since all resets cause program execution to begin at the same location (0x0000) software can read the PORSF flag to determine if a power-up was the cause of reset. The content of internal data memory should be assumed to be undefined after a power-on reset. The V_{DD} monitor is enabled following a power-on reset.

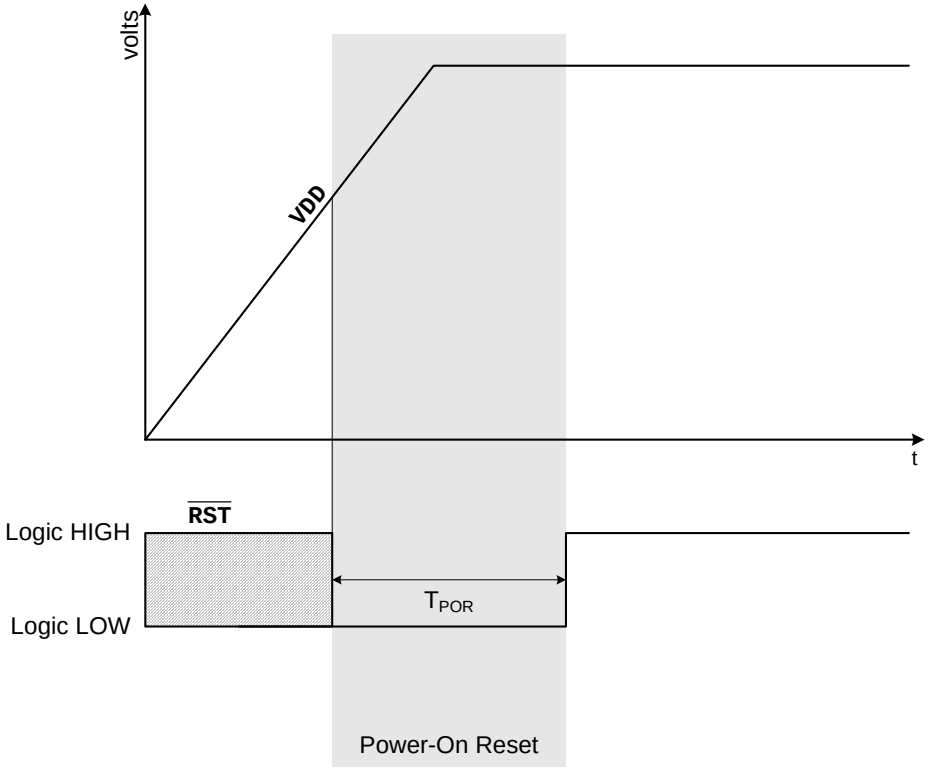

Figure 22.2. Power-on Reset Timing

23.3. SPI0 Slave Mode Operation

When SPI0 is enabled and not configured as a master, it will operate as a SPI slave. As a slave, bytes are shifted in through the MOSI pin and out through the MISO pin by a master device controlling the SCK signal. A bit counter in the SPI0 logic counts SCK edges. When 8 bits have been shifted through the shift register, the SPIF flag is set to logic 1, and the byte is copied into the receive buffer. Data is read from the receive buffer by reading SPI0DAT. A slave device cannot initiate transfers. Data to be transferred to the master device is pre-loaded into the shift register by writing to SPI0DAT. Writes to SPI0DAT are double-buffered, and are placed in the transmit buffer first. If the shift register is empty, the contents of the transmit buffer will immediately be transferred into the shift register. When the shift register already contains data, the SPI will load the shift register with the transmit buffer's contents after the last SCK edge of the next (or current) SPI transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic 0, and disabled when NSS is logic 1. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 23.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

The 3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is no way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 23.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

23.4. SPI0 Interrupt Sources

When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic 1:

All of the following bits must be cleared by software.

- The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic 1 at the end of each byte transfer. This flag can occur in all SPI0 modes.
- The Write Collision Flag, WCOL (SPI0CN.6) is set to logic 1 if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written.This flag can occur in all SPI0 modes.
- The Mode Fault Flag MODF (SPI0CN.5) is set to logic 1 when SPI0 is configured as a master, and for multi-master mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic 0 to disable SPI0 and allow another master device to access the bus.
- The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic 1 when configured as a slave, and a transfer is completed and the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.

23.5. Serial Clock Phase and Polarity

Four combinations of serial clock phase and polarity can be selected using the clock control bits in the SPI0 Configuration Register (SPI0CFG). The CKPHA bit (SPI0CFG.5) selects one of two clock phases (edge used to latch the data). The CKPOL bit (SPI0CFG.4) selects between an active-high or active-low clock. Both master and slave devices must be configured to use the same clock phase and polarity. SPI0

Table 23.1. SPI Slave Timing Parameters

Parameter	Description	Min	Max	Units
Master Mode Timing (See Figure 23.8 and Figure 23.9)				
T_{MCKH}	SCK High Time	1 x T_{SYSCLK}	—	ns
T_{MCKL}	SCK Low Time	1 x T_{SYSCLK}	—	ns
T_{MIS}	MISO Valid to SCK Shift Edge	1 x T_{SYSCLK} + 20	—	ns
T_{MIH}	SCK Shift Edge to MISO Change	0	—	ns
Slave Mode Timing (See Figure 23.10 and Figure 23.11)				
T_{SE}	NSS Falling to First SCK Edge	2 x T_{SYSCLK}	—	ns
T_{SD}	Last SCK Edge to NSS Rising	2 x T_{SYSCLK}	—	ns
T_{SEZ}	NSS Falling to MISO Valid	—	4 x T_{SYSCLK}	ns
T_{SDZ}	NSS Rising to MISO High-Z	—	4 x T_{SYSCLK}	ns
T_{CKH}	SCK High Time	5 x T_{SYSCLK}	—	ns
T_{CKL}	SCK Low Time	5 x T_{SYSCLK}	—	ns
T_{SIS}	MOSI Valid to SCK Sample Edge	2 x T_{SYSCLK}	—	ns
T_{SIH}	SCK Sample Edge to MOSI Change	2 x T_{SYSCLK}	—	ns
T_{SOH}	SCK Shift Edge to MISO Change	—	4 x T_{SYSCLK}	ns
T_{SLH}	Last SCK Edge to MISO Change (CKPHA = 1 ONLY)	6 x T_{SYSCLK}	8 x T_{SYSCLK}	ns
Note: T_{SYSCLK} is equal to one period of the device system clock (SYSCLK).				

24.1. Supporting Documents

It is assumed the reader is familiar with or has access to the following supporting documents:

1. The I^{2}C-Bus and How to Use It (including specifications), Philips Semiconductor.
2. The I^{2}C-Bus Specification—Version 2.0, Philips Semiconductor.
3. System Management Bus Specification—Version 1.1, SBS Implementers Forum.

24.2. SMBus Configuration

Figure 24.2 shows a typical SMBus configuration. The SMBus specification allows any recessive voltage between 3.0 V and 5.0 V; different devices on the bus may operate at different voltage levels. However, the maximum voltage on any port pin must conform to the electrical characteristics specifications. The bi-directional SCL (serial clock) and SDA (serial data) lines must be connected to a positive power supply voltage through a pullup resistor or similar circuit. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines, so that both are pulled high (recessive state) when the bus is free. The maximum number of devices on the bus is limited only by the requirement that the rise and fall times on the bus not exceed 300 ns and 1000 ns, respectively.

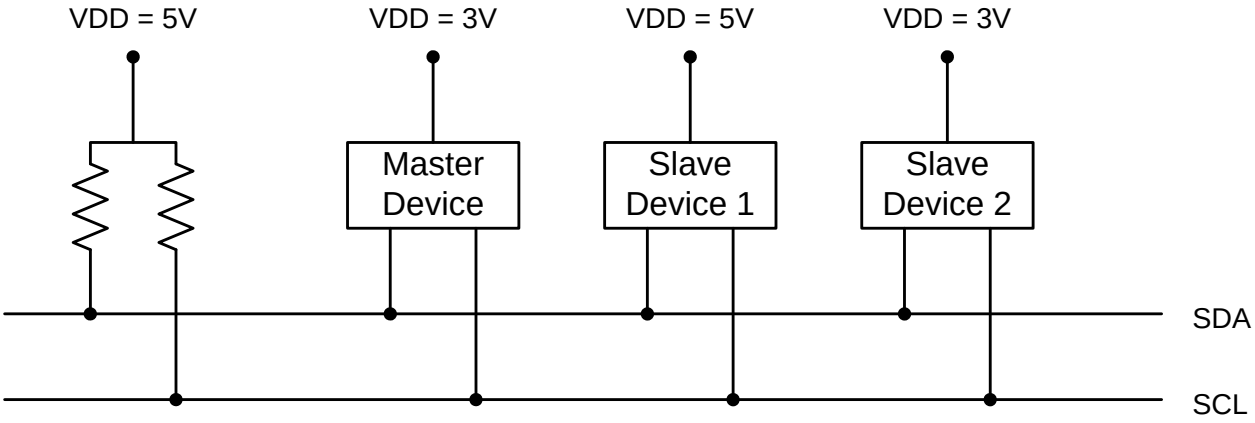

Figure 24.2. Typical SMBus Configuration

24.3. SMBus Operation

Two types of data transfers are possible: data transfers from a master transmitter to an addressed slave receiver (WRITE), and data transfers from an addressed slave transmitter to a master receiver (READ). The master device initiates both types of data transfers and provides the serial clock pulses on SCL. The SMBus interface may operate as a master or a slave, and multiple master devices on the same bus are supported. If two or more masters attempt to initiate a data transfer simultaneously, an arbitration scheme is employed with a single master always winning the arbitration. It is not necessary to specify one device as the Master in a system; any device who transmits a START and a slave address becomes the master for the duration of that transfer.

A typical SMBus transaction consists of a START condition followed by an address byte (Bits7–1: 7-bit slave address; Bit0: R/W direction bit), one or more bytes of data, and a STOP condition. Bytes that are received (by a master or slave) are acknowledged (ACK) with a low SDA during a high SCL (see Figure 24.3). If the receiving device does not ACK, the transmitting device will read a NACK (not acknowledge), which is a high SDA during a high SCL.

The direction bit (R/W) occupies the least-significant bit position of the address byte. The direction bit is set to logic 1 to indicate a "READ" operation and cleared to logic 0 to indicate a "WRITE" operation.

Register 25.8. TMR2CN: Timer 2 Control

Bit	7	6	5	4	3	2	1	0
Name	TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2	Reserved	T2XCLK
Type	RW	RW	RW	RW	RW	RW	R	RW
Reset	0	0	0	0	0	0	0	0
SFR Address: 0xC8 (bit-addressable)								

Table 25.10. TMR2CN Register Bit Descriptions

Bit	Name	Function
7	TF2H	**Timer 2 High Byte Overflow Flag.** Set by hardware when the Timer 2 high byte overflows from 0xFF to 0x00. In 16 bit mode, this will occur when Timer 2 overflows from 0xFFFF to 0x0000. When the Timer 2 interrupt is enabled, setting this bit causes the CPU to vector to the Timer 2 interrupt service routine. This bit is not automatically cleared by hardware.
6	TF2L	**Timer 2 Low Byte Overflow Flag.** Set by hardware when the Timer 2 low byte overflows from 0xFF to 0x00. TF2L will be set when the low byte overflows regardless of the Timer 2 mode. This bit is not automatically cleared by hardware.
5	TF2LEN	**Timer 2 Low Byte Interrupt Enable.** When set to 1, this bit enables Timer 2 Low Byte interrupts. If Timer 2 interrupts are also enabled, an interrupt will be generated when the low byte of Timer 2 overflows.
4	TF2CEN	**Timer 2 Capture Enable.** When set to 1, this bit enables Timer 2 Capture Mode. If TF2CEN is set and Timer 2 interrupts are enabled, an interrupt will be generated on a falling edge of the selected T2 input pin, and the current 16-bit timer value in TMR2H:TMR2L will be copied to TMR2RLH:TMR2RLL.
3	T2SPLIT	**Timer 2 Split Mode Enable.** When this bit is set, Timer 2 operates as two 8-bit timers with auto-reload. 0: Timer 2 operates in 16-bit auto-reload mode. 1: Timer 2 operates as two 8-bit auto-reload timers.
2	TR2	**Timer 2 Run Control.** Timer 2 is enabled by setting this bit to 1. In 8-bit mode, this bit enables/disables TMR2H only; TMR2L is always enabled in split mode.
1	Reserved	Must write reset value.